

Table 1: Signal Pin Reference

<i>Signal</i>	<i>Type</i>	<i>Level</i>	<i># Pins</i>	<i>Description</i>
DIN, NDIN	In	ECL	2	Data Input and Data Reference, On-chip 50Ω Termination
MK, NMK	Out	ECL	2	Data Density Differential Outputs
NIOUT	Out		1	Laser Modulation Current Output (Complementary)
IOUT	Out		1	Laser Modulation Current Output (To Laser Cathode)
VSS	Pwr	Pwr	3	Negative Voltage Rail
GND	Pwr	Pwr	4	Positive Voltage Rail
VIP	In	DC	1	Modulation Gate Node
MIP	In	DC	1	Modulation Source Node
VIB	In	DC	1	Bias Gate Node
MIB	In	DC	1	Bias Source Node
IBIAS	Out	DC	1	Laser Bias Output (To Laser Cathode)
CLK, NCLK	In	ECL	2	Clock Input and Clock Reference, On-chip 50Ω Termination
DINTERM	In	DC	1	Data Reference
CLKTERM	In	DC	1	Clock Reference
DCC	In	DC	1	Duty Cycle Control, Leave Floating
SEL	In	DC	1	Clk/Non-clk Data Select
Total Pins			24	

Table 2: Mux Select Logic Table

<i>SEL</i>	<i>Mode Select</i>
V _{SS}	Clocked Data In
GND	Non-clocked Data In
N/C	Non-clocked Data In

Table 3: Absolute Maximum Ratings

<i>Symbol</i>	<i>Rating</i>	<i>Limit</i>
V _{SS}	Negative Power Supply Voltage	V _{CC} to -6.0V
T _j	Maximum Junction Temperature	-55C to +125C
T _{stg}	Storage Temperature	-65C to +150C

Table 4: High Speed Inputs and ECL Outputs

<i>Symbol</i>	<i>Parameter</i>	<i>Min</i>	<i>Max</i>	<i>Units</i>	<i>Conditions</i>
V _{IN}	Single-ended Input Voltage Swing	300	1500	mVp-p	V _{CM} = -2.0V
V _{CM}	Differential Input Common Mode Range	-2.3	-1.3	V	V _{SS} = -5.2V
V _{OH}	ECL Output High Voltage	-1200		mV	50 Ohms to -2.0V
V _{OL}	ECL Output Low Voltage		-1600	mV	50 Ohms to -2.0V
V _{IN}	On-Chip Terminations	35	65	Ohms	—

Advance Product Information

VSC7927

SDH/SONET 2.5Gb/s
Laser Diode Driver

Table 5: Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Units	Conditions
GND	Positive Voltage Rail		0		V	
VSS	Negative Voltage Rail	-5.5	-5.2	-4.9	V	
T _{cj}	*Operational Temperature	-40		85**	C	Power dissipation = 1.25W
T _j	Junction Temperature			125	C	

*Lower limit of specification is ambient temperature and upper limit is case temperature.

**See section "Calculation of the Maximum Case Temperature" for detailed maximum temperature calculations.

Table 6: Power Dissipation

Symbol	Parameter	Min	Typ	Max	Units	Conditions
I _{VSS}	Power Supply Current (VSS)	-	-	150	mA	V _{SS} = -5.5, I _{MOD} = I _{BIAS} = 0 mA
Pd	Total Power Dissipation	-	-	825	mW	V _{SS} = -5.5, I _{MOD} = I _{BIAS} = 0 mA, R _{load} = 25 Ohms to GND
Pdmax	Maximum Power Dissipation	-	-	1430	mW	V _{SS} = -5.5, I _{MOD} = 60mA, I _{BIAS} = 50 mA, I _{OUT} = 0 Volts

Table 7: Laser Driver DC Electrical Specifications

Symbol	Parameter	Min	Typ	Max	Units	Conditions
I _{BIAS}	Programmable Laser Bias Current	2		50	mA	-
I _{MOD}	Programmable Modulation Current	2	-	60	mA	
V _{IB}	Laser Bias Control Voltage			V _{SS} + 2.1	V	I _{BIAS} = 50 mA
V _{IP}	Laser Modulation Control Voltage			V _{SS} + 2.1	V	I _{MOD} = 60 mA
V _{OCM}	Output Voltage Compliance			GND -2.5V	V	V _{SS} = -5.2V

Table 8: Laser Driver AC Electrical Specifications

Symbol	Parameter	Min	Typ	Max	Units	Conditions
t _r t _f	Output Rise and Fall Times			100	ps	25 Ohm load, 20%-80%, 20mA < I _{MOD} < 60mA, I _{BIAS} = 20mA
t _{su}	t Setup Data to Clock		50		ps	
t _h	t Hold		50		ps	

Table 9: Package Thermal Specifications

Symbol	Parameter	Min	Typ	Max	Units	Conditions
θ _{JCC}	Thermal Resistance from Junction to Case		25		°C/W	Ceramic Package
θ _{JCMG}	Thermal Resistance from Junction to Case		32		°C/W	Metal Glass Package

Calculation of the Maximum Case Temperature

The VSC7927 is designed to operate with a maximum junction temperature of 125°C. The rise from the case to junction is determined by the power dissipation of the device. The power dissipation is determined by the V_{SS} current plus the operating I_{MOD} and I_{BIAS} currents.

The power of the chip is determined by the following formula:

$$P_D = (-V_{SS} * I_{SS}) + ((V_{IOUT} - V_{SS}) * I_{MOD}) + ((V_{IBIAS} - V_{SS}) * I_{BIAS})$$

For example with:

$$\begin{aligned} V_{SS} &= -5.2V \\ I_{MOD} &= 40mA \\ I_{BIAS} &= 20mA \\ V_{IBIAS} &= -2.0V \\ V_{IOUT} &= -2.0V \end{aligned}$$

$$P_D = (-5.2 * 150mA) + ((5.2 - 2.0) * 40mA) + ((5.2 - 2.0) * 20mA)$$

$$P_D = 780mW + 128mW + 64mW = 972mW$$

The thermal rise from junction to case is $\theta_{JC} * P_D$. For the metal glass package, $\theta_{JC} = 32 \text{ }^\circ\text{C/W}$. Thus the thermal rise is:

$$32^\circ\text{C/W} * 1.336W = 31.1^\circ\text{C}$$

The maximum case temperature is:

$$125^\circ\text{C} - 31.1^\circ\text{C} = 93.9^\circ\text{C}$$

The absolute maximum power dissipation of the device is at:

$$\begin{aligned} V_{SS} &= -5.5V \\ I_{MOD} &= 60mA \\ I_{BIAS} &= 50mA \\ V_{IBIAS} &= 0V \\ V_{IOUT} &= 0V \end{aligned}$$

$$P_D = (5.5 * 150mA) + (5.5 * 60mA) + (5.5mA * 50mA) \quad P_D = 1.43W$$

This will net a maximum junction to case thermal rise of: $1.43W * 32^\circ\text{C/W} = 45.8^\circ\text{C}$

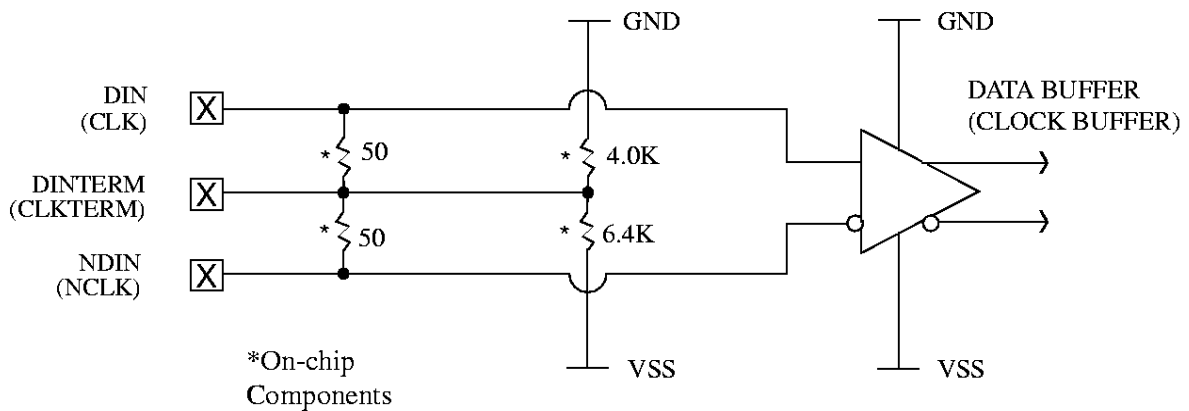
This situation will allow maximum case temperature of: $125^\circ\text{C} - 58^\circ\text{C} = 79.2^\circ\text{C}$

Advance Product Information

VSC7927

SDH/SONET 2.5Gb/s
Laser Diode Driver

Figure 1: On-chip Data and Clock Input Configuration



DINTERM to -2.0V for Differential ECL Inputs

Figure 2: Single Ended Operation

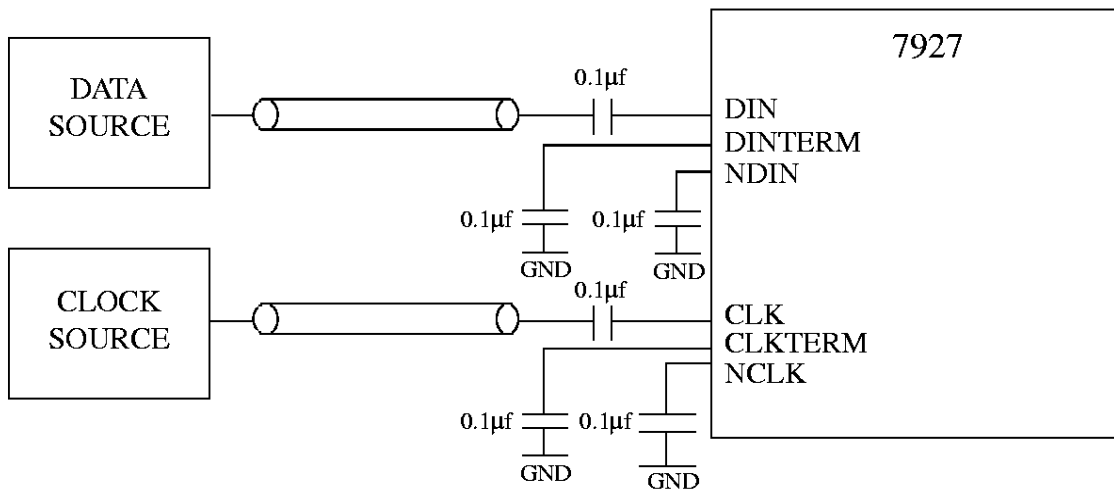


Figure 3: Single Ended AC Coupled

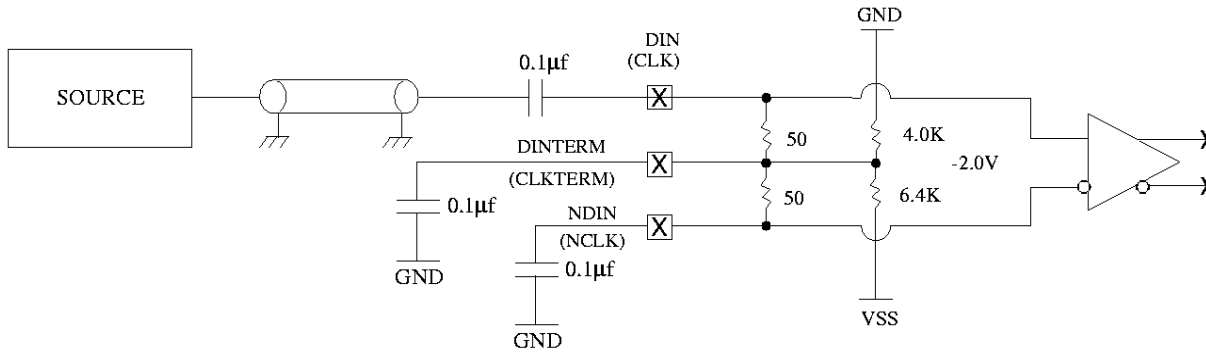


Figure 4: Differential AC Coupled

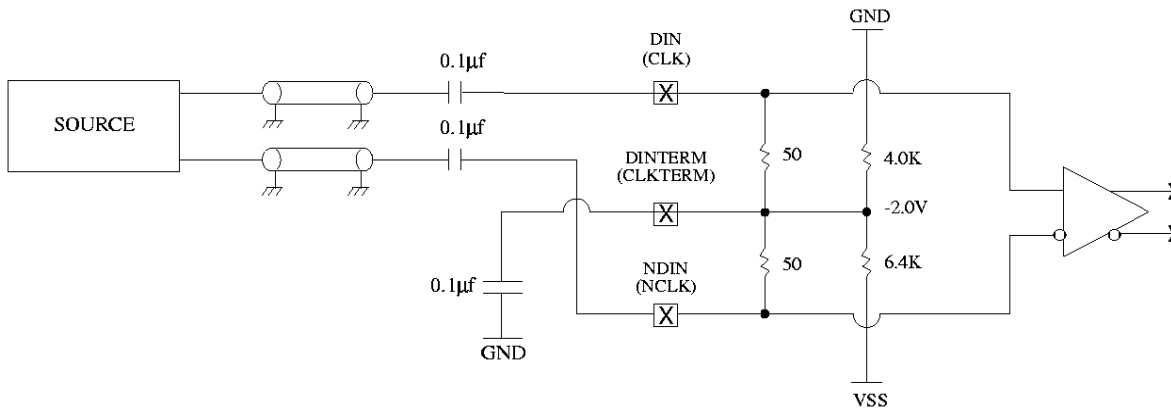
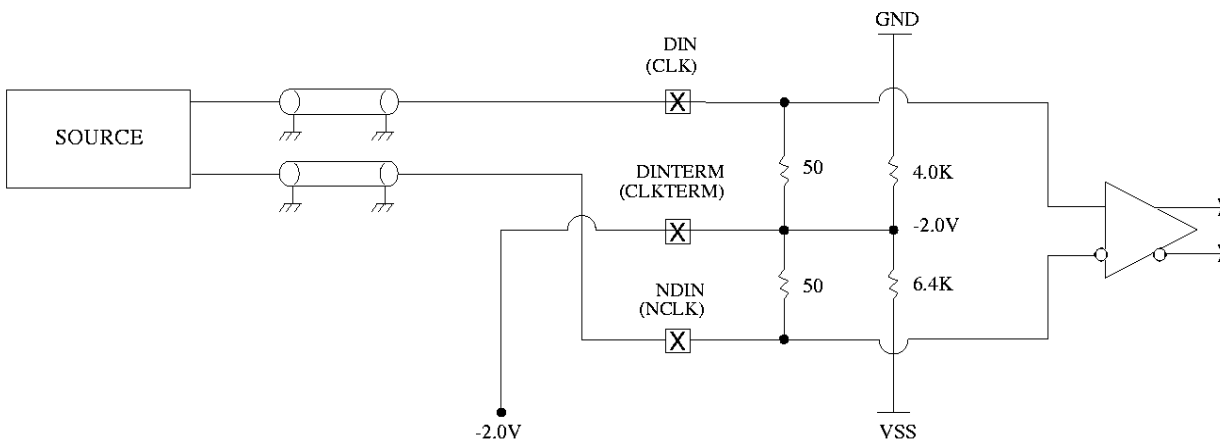


Figure 5: Differential DC Coupled

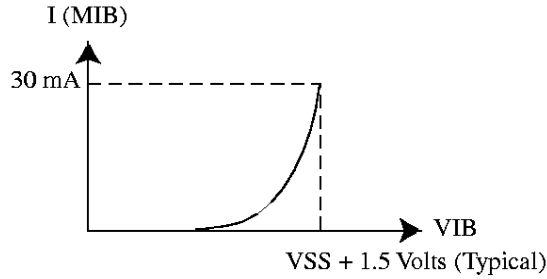


Advance Product Information

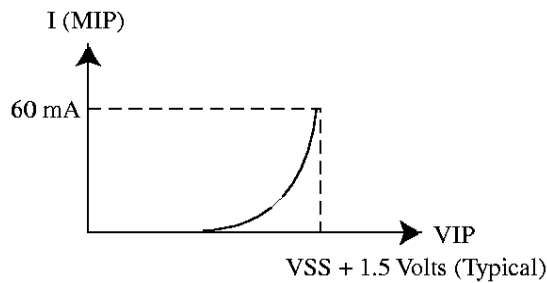
VSC7927

SDH/SONET 2.5Gb/s
Laser Diode Driver

Figure 6: Control Signals VIP and VIB

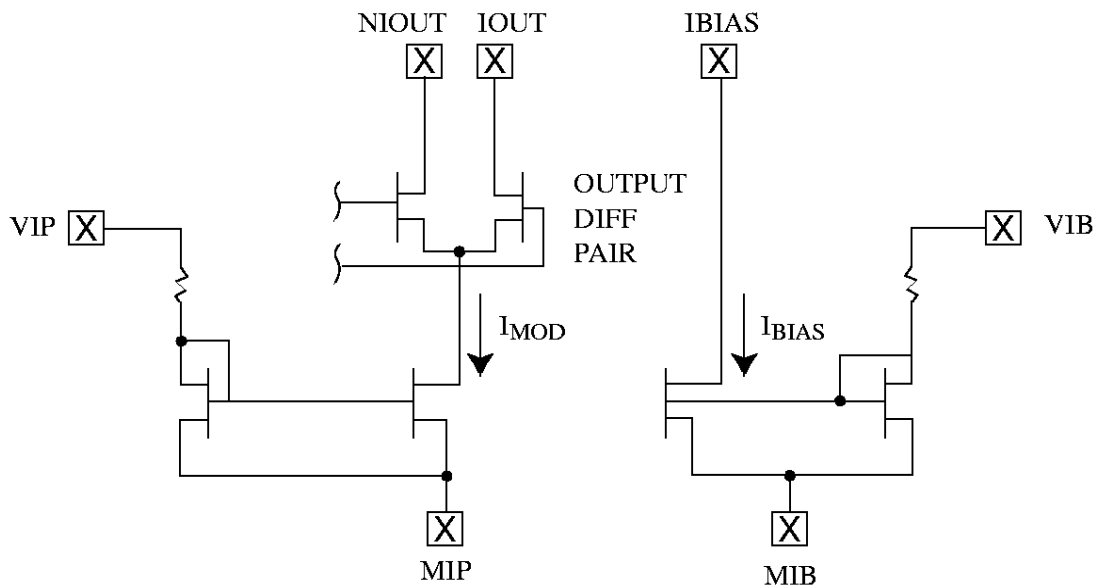


Typical Bias Current v.s. Bias Voltage

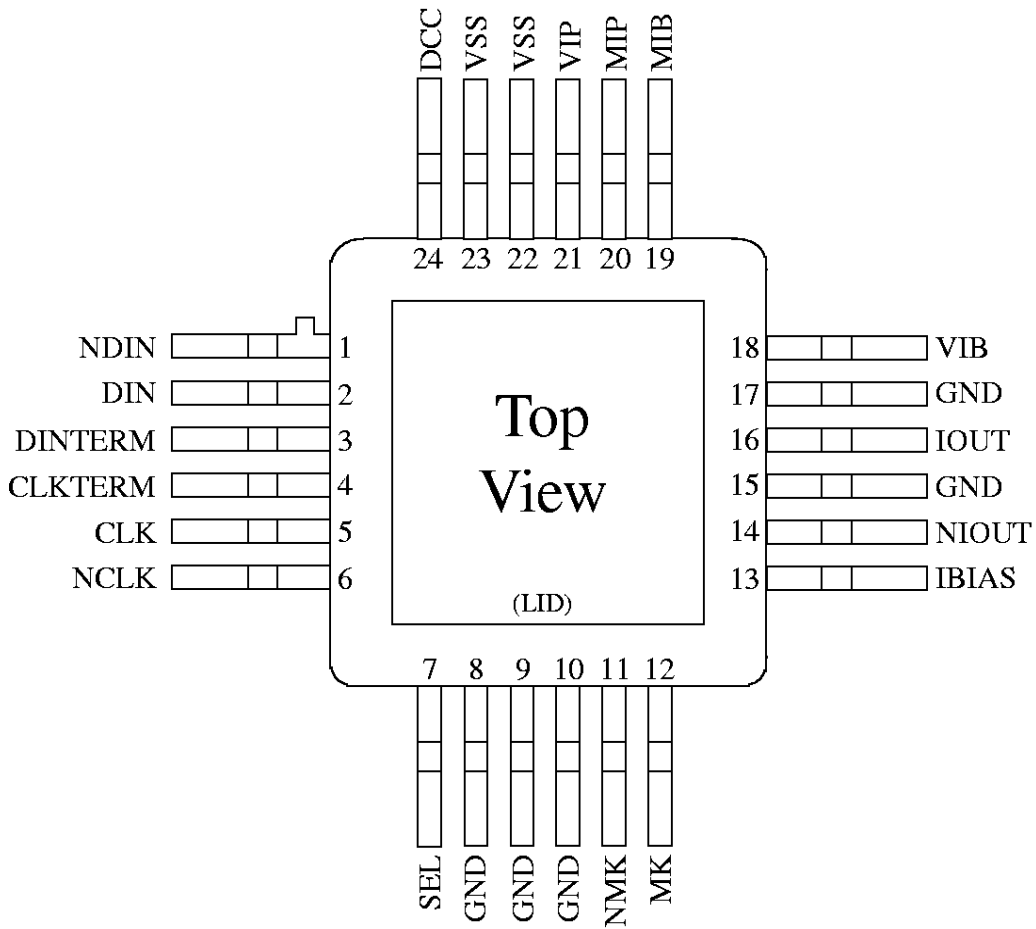


Typical Modulation Current v.s. Modulation Voltage

Figure 7: Simplified Output Structure



Pin Diagram for 24 Pin Metal-Glass Package

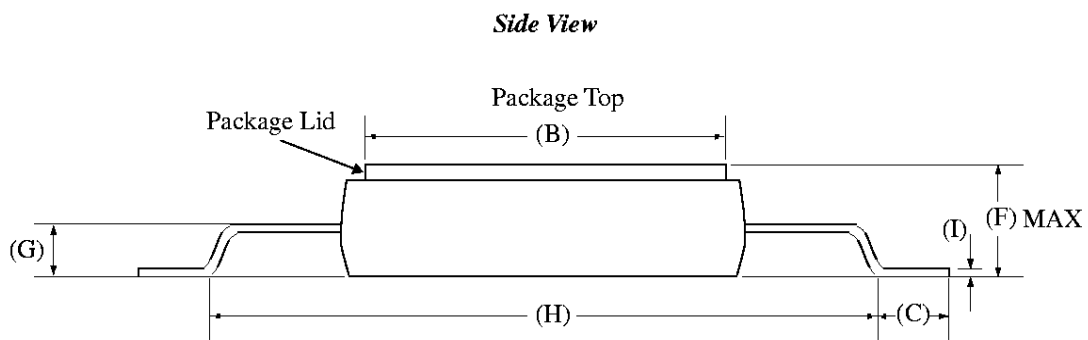
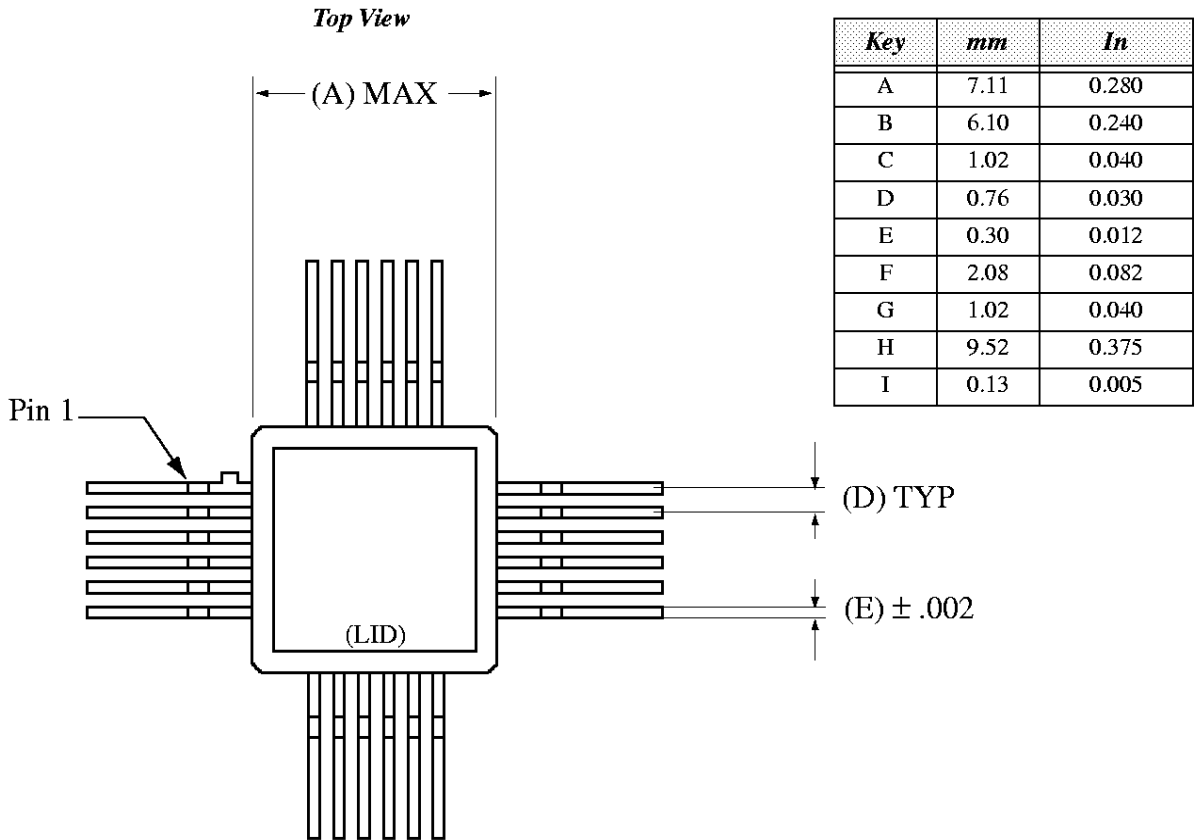


Note: Package bottom plate is connected to GND within the package.
Package lid is electrically unconnected.

Advance Product Information
VSC7927

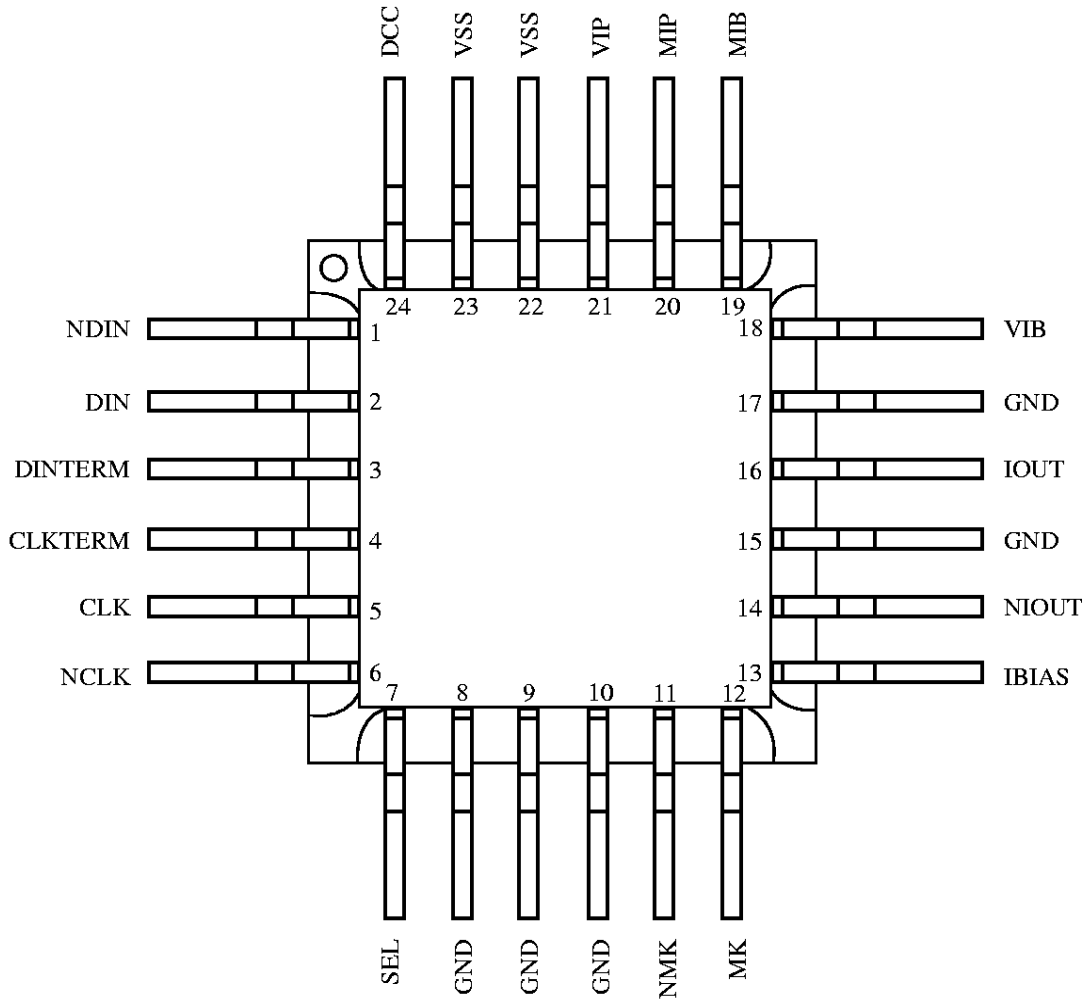
SDH/SONET 2.5Gb/s
 Laser Diode Driver

Package Information - 24 Pin Metal-Glass Package



NOTES: Drawing not to scale.
 Package #: 101-000-0 Issue #:1

Pin Diagram for 24 Pin Ceramic Package



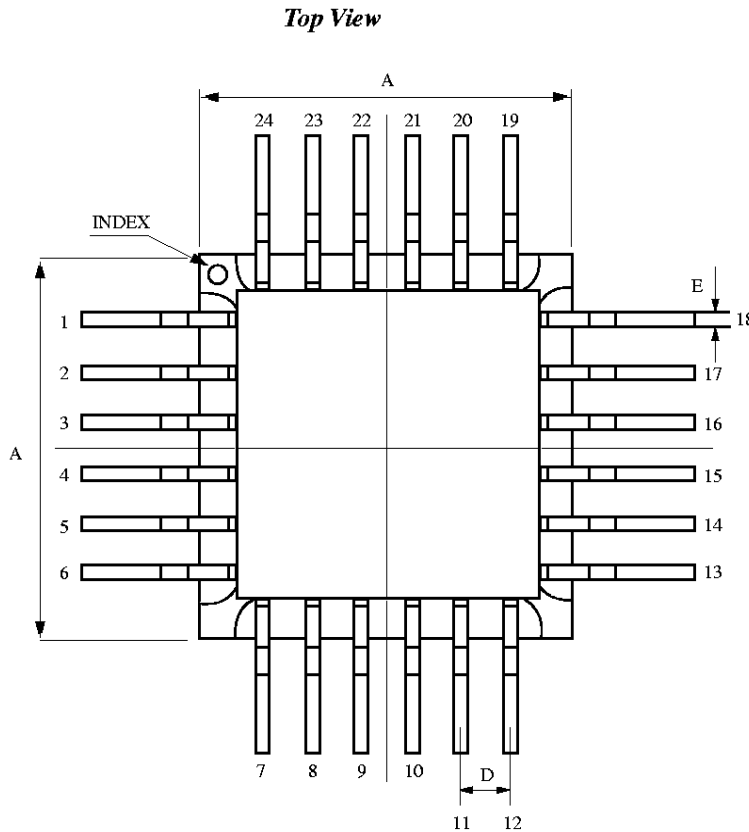
Note: Package lid and bottom heat spreader are electrically connected to GND within the package.

Advance Product Information

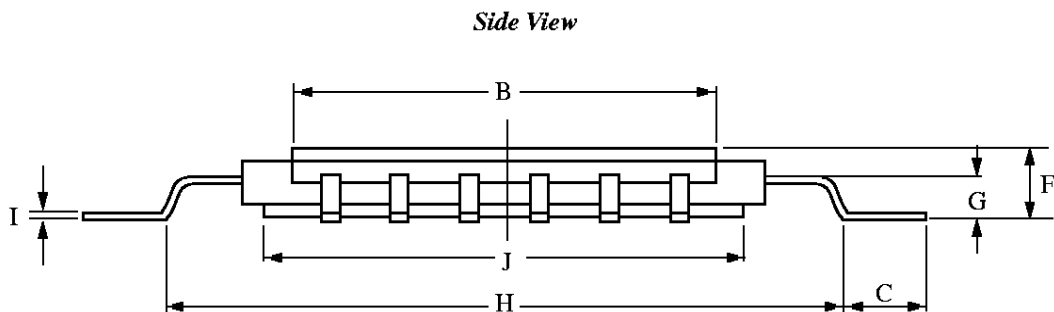
VSC7927

SDH/SONET 2.5Gb/s
Laser Diode Driver

Package Information - 24 Pin Ceramic Package



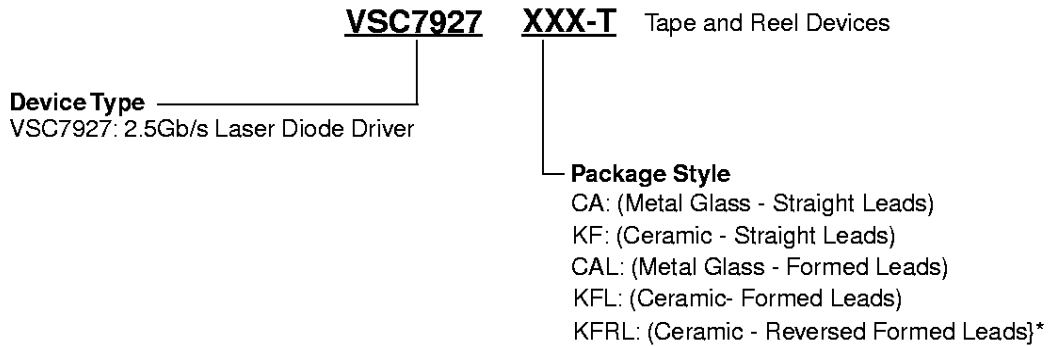
Key	mm	In
A	9.5	0.374
B	7.7	0.303
C	2.0	0.079
D	1.27	0.050
E	0.30	0.012
F	1.7	0.067
G	0.6	0.024
H	11.5	0.453
I	0.125	0.005
J	8.51	0.335



NOTES: Drawing not to scale.
Package #: 101-000-0 Issue #:1

Ordering Information

The order number for this product is formed by a combination of the device number, and package style.



*Reversed Formed Leads: Package leads have the same profile and dimensions, but heat spreader is away from board

Notice

This document contains information about a new product during its fabrication or early sampling phase of development. The information in this document is based on design targets, simulation results or early prototype test results. Characteristic data and other specifications are subject to change without notice. Therefore the reader is cautioned to confirm that this datasheet is current prior to design or order placement.

Warning

Vitesse Semiconductor Corporation's products are not intended for use in life support appliances, devices or systems. Use of a Vitesse product in such applications without the written consent is prohibited